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(12) **United States Design Patent**
Sheng et al.

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(54) **HOUSING OF A LIGHT EMITTING DIODE PACKAGE**

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(73) Assignee: **Everlight Electronics Co., Ltd.**, Taipei (TW)

(**) Term: **14 Years**

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(22) Filed: **Aug. 6, 2009**

Related U.S. Application Data

(63) Continuation of application No. 29/306,131, filed on Apr. 3, 2008, now Pat. No. Des. 602,447.

(51) **LOC (9) Cl.** **13-03**
(52) **U.S. Cl.** **D13/180**
(58) **Field of Classification Search** D13/180; D26/2; 257/79, 80, 81, 88, 89, 95, 98, 99, 257/100; 313/483, 498, 500; 362/555, 800
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a housing of a light emitting diode package, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a housing of a light emitting diode package showing our new design;

FIG. **2** is a front view thereof;

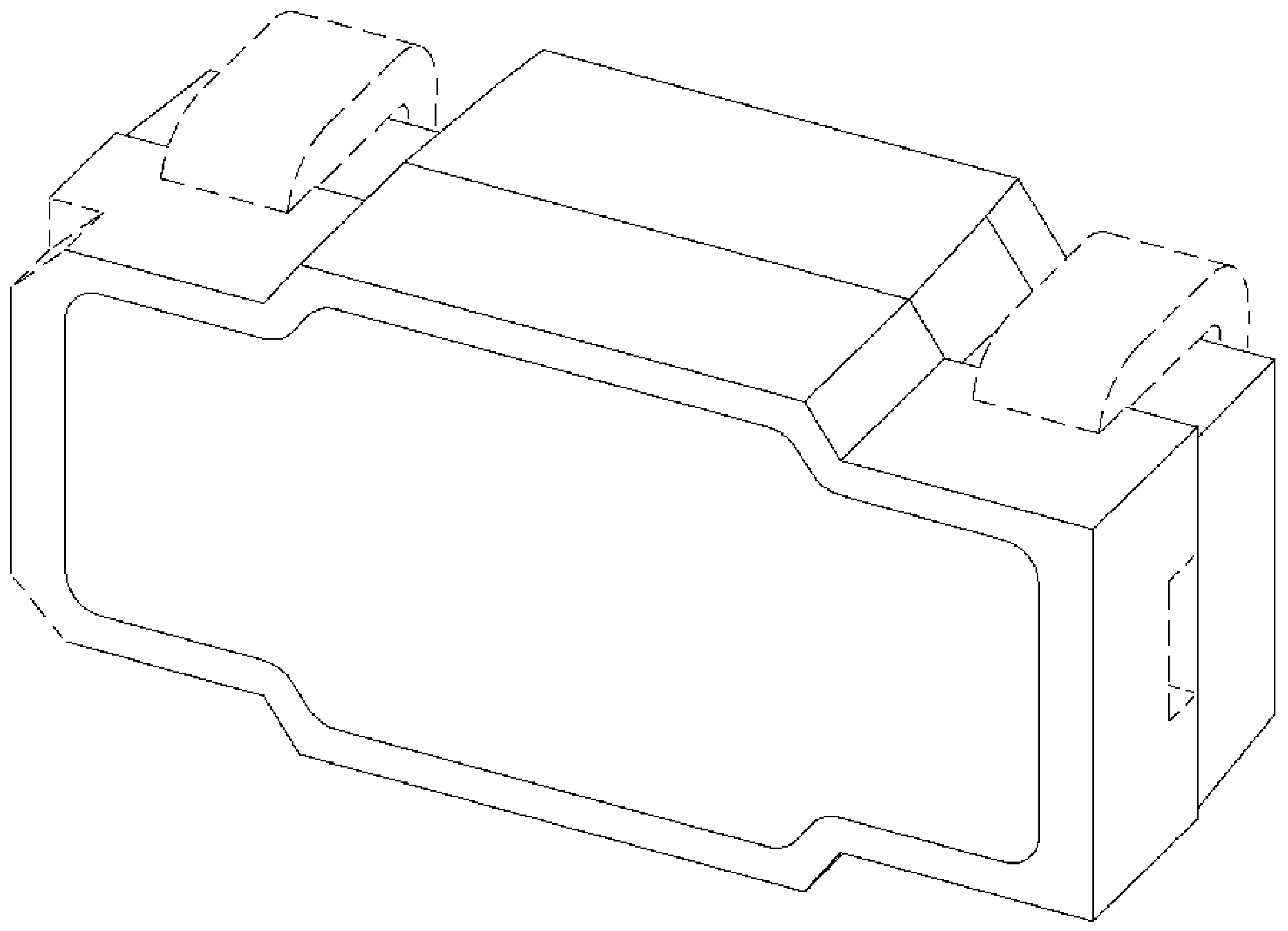
FIG. **3** is a rear view thereof wherein the broken line showing portion of the diode package is for illustrative purpose only and forms no part of the claimed design;

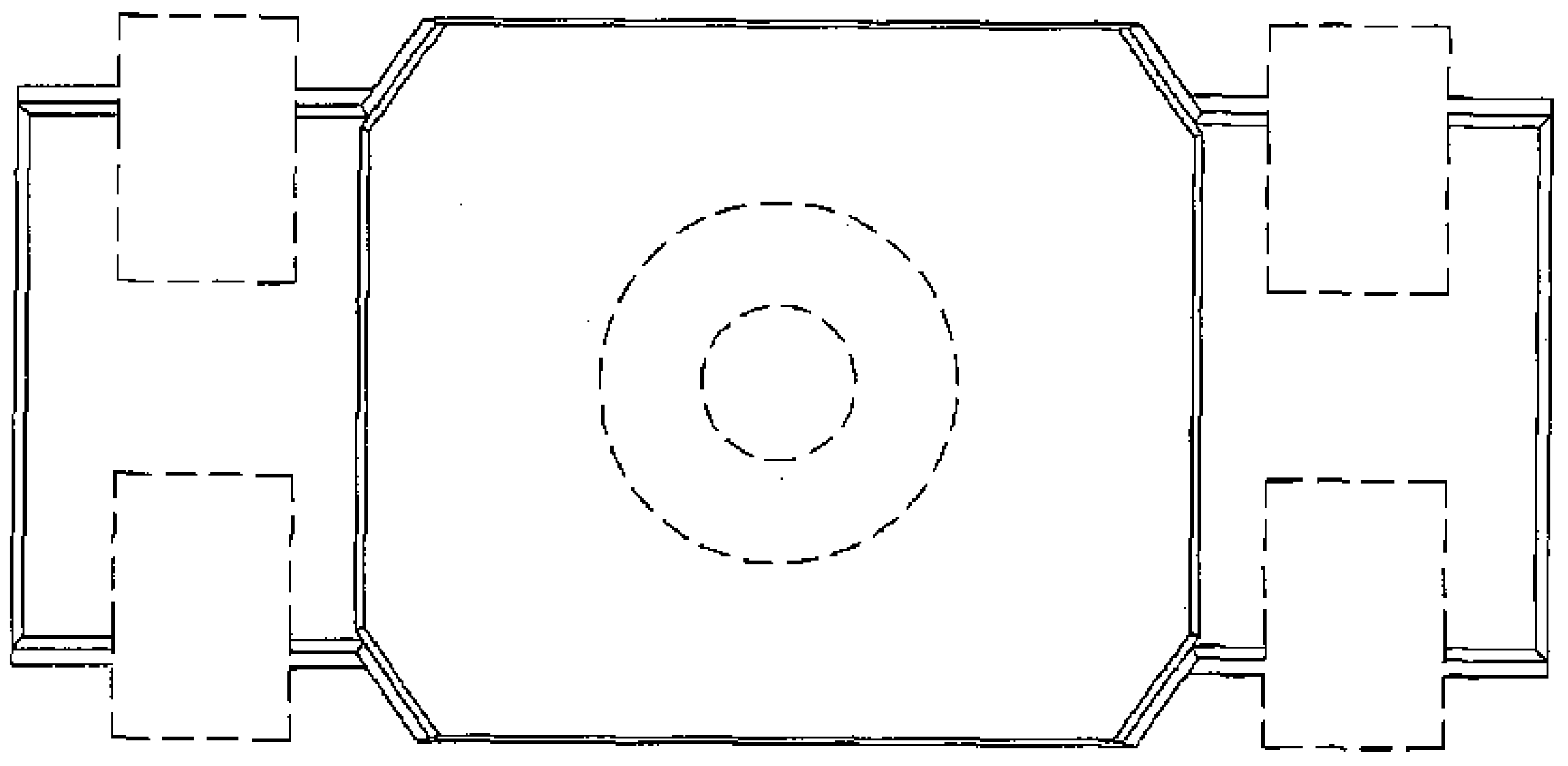
FIG. **4** is a left side view thereof;

FIG. **5** is a right side view thereof; and,

FIG. **6** is a top view thereof, the bottom view being a mirror image of the top side view.

1 Claim, 4 Drawing Sheets





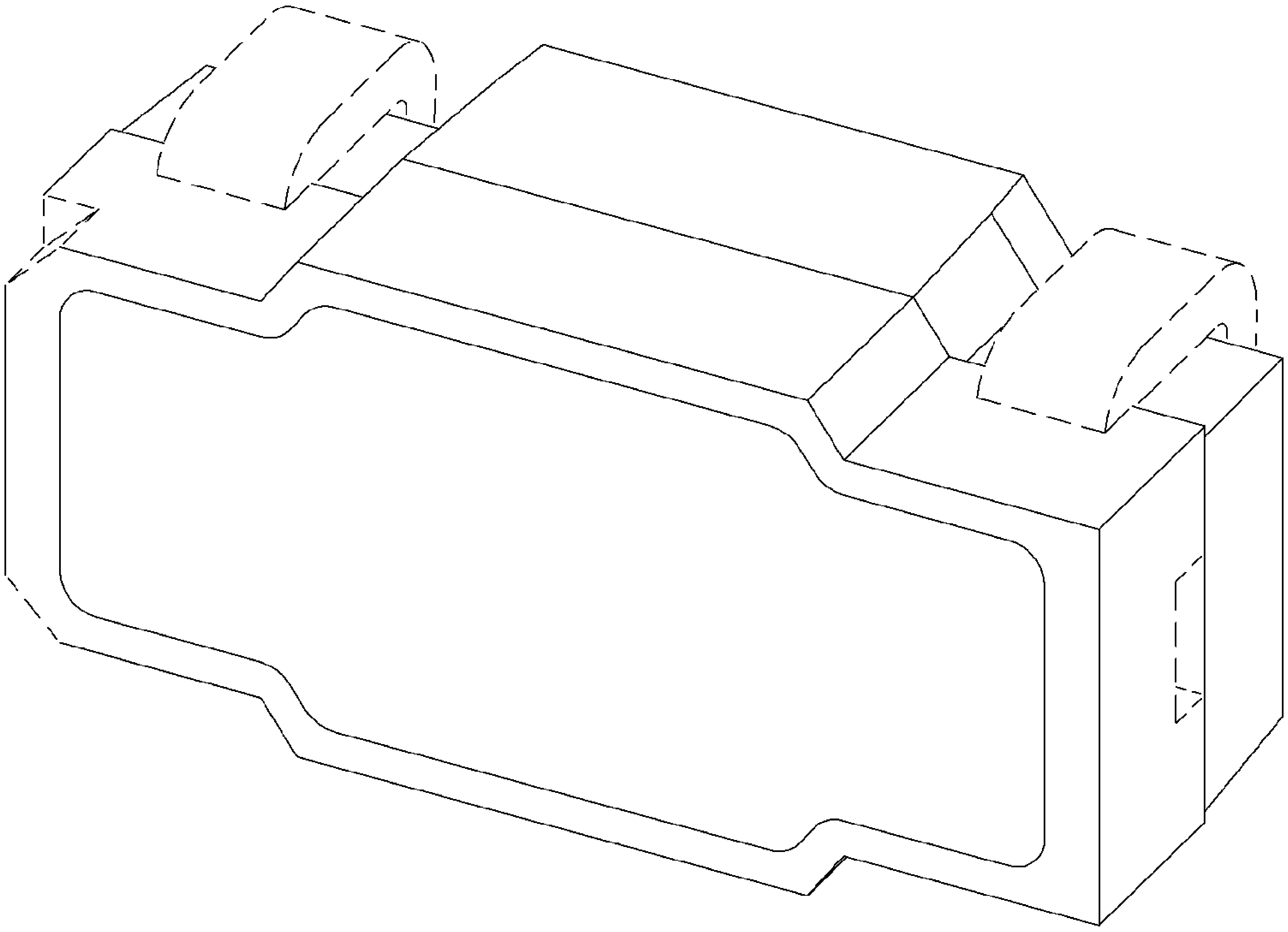


FIG. 1

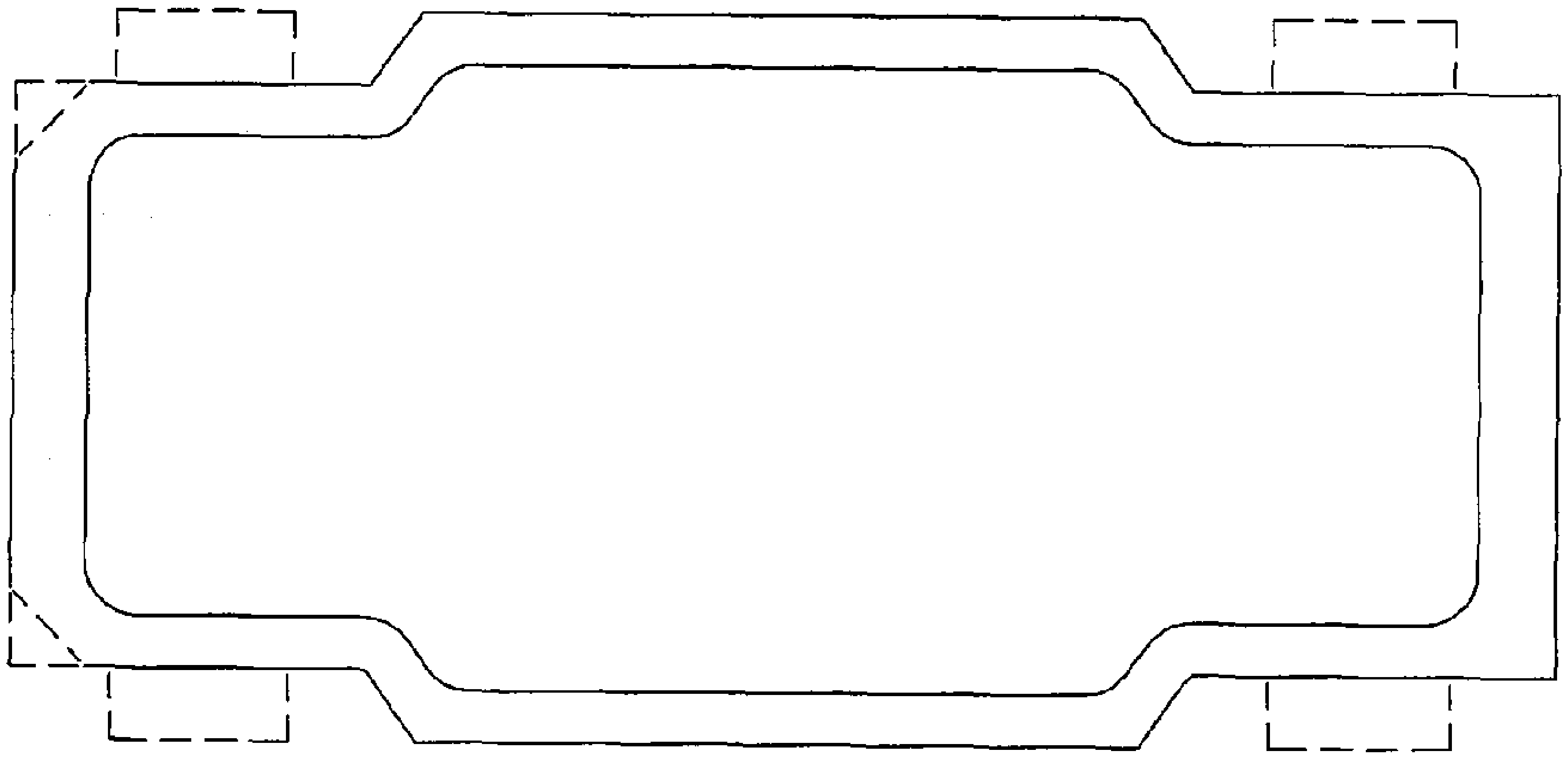


FIG. 2

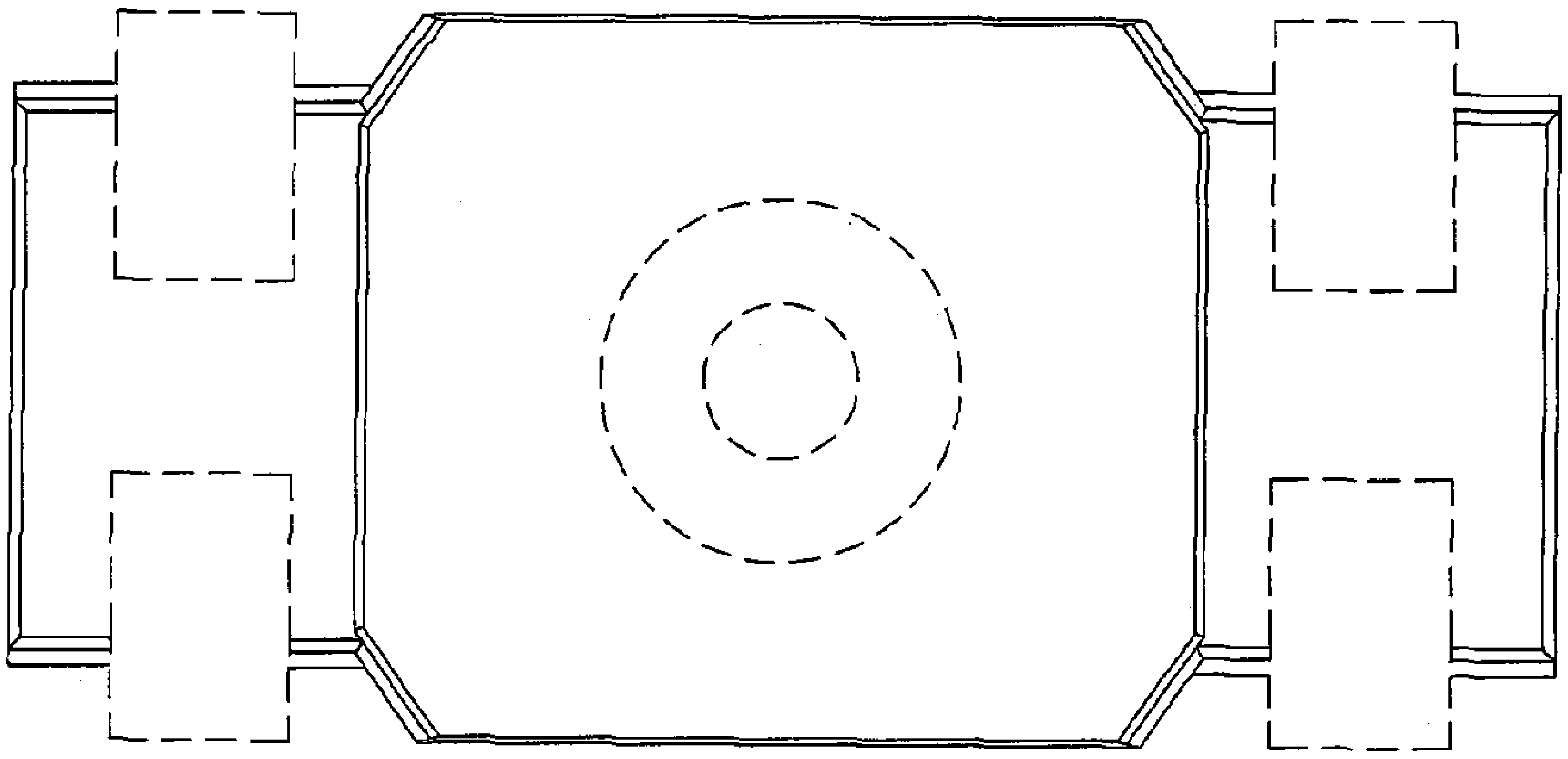


FIG. 3

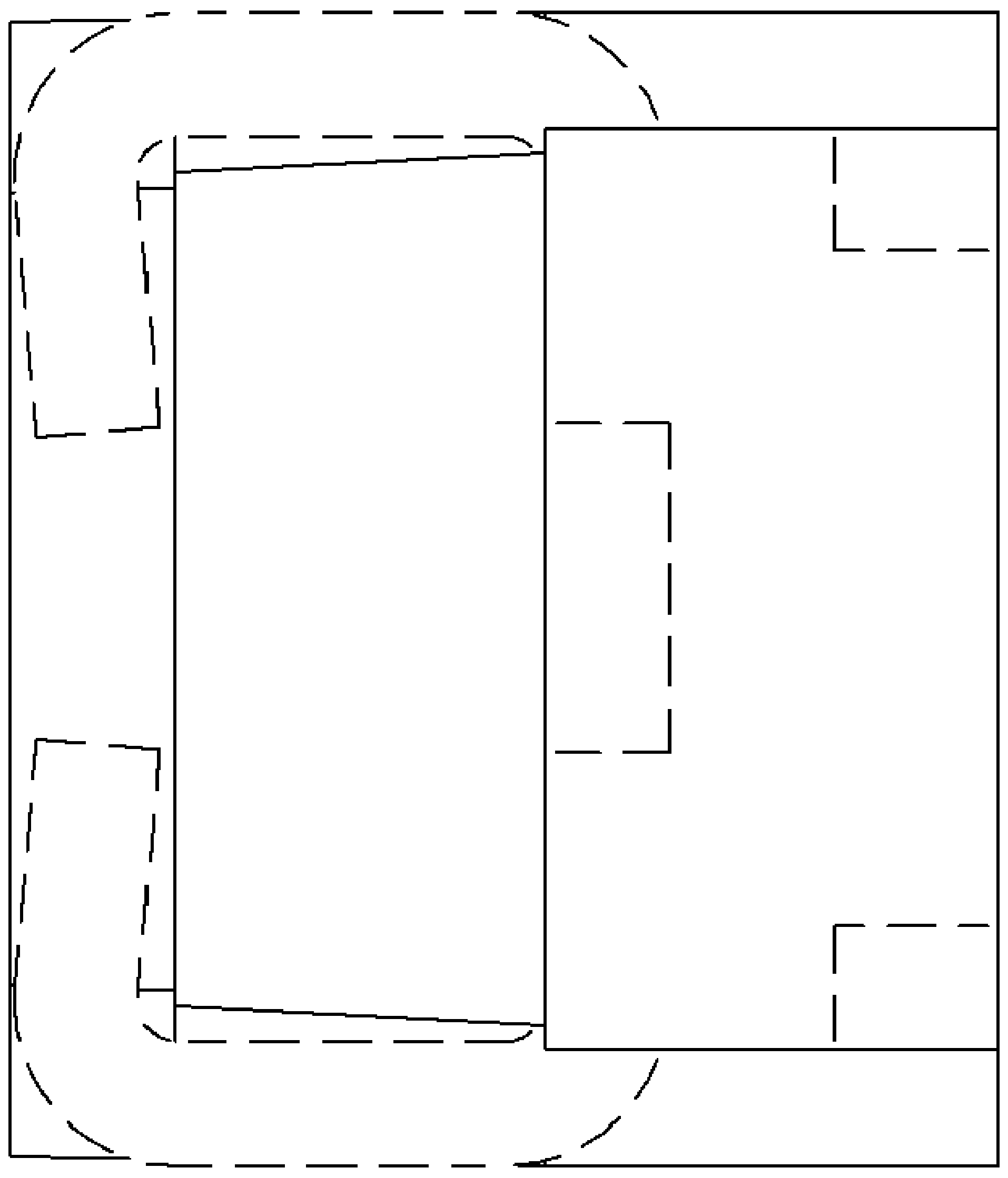


FIG. 4

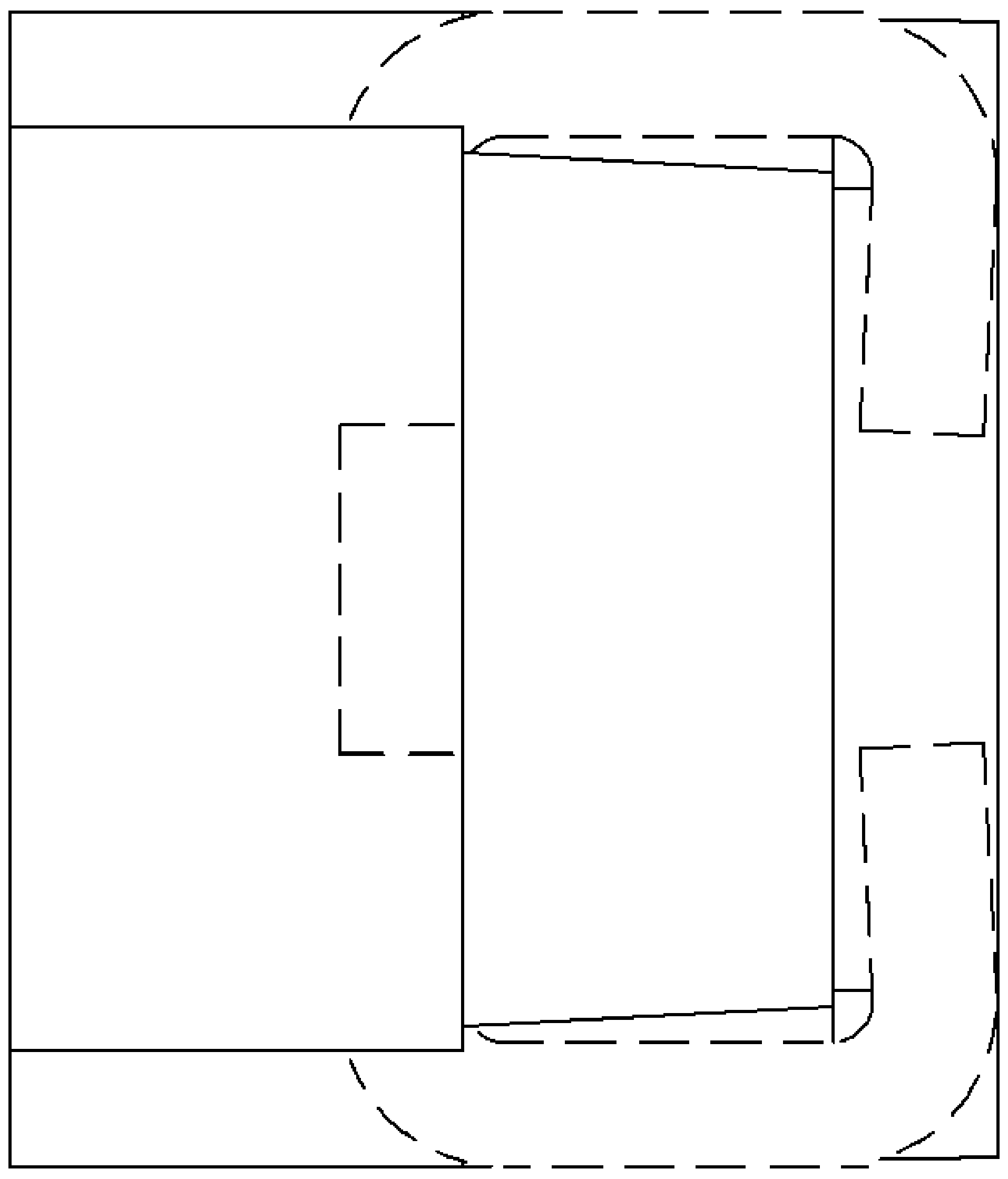


FIG. 5

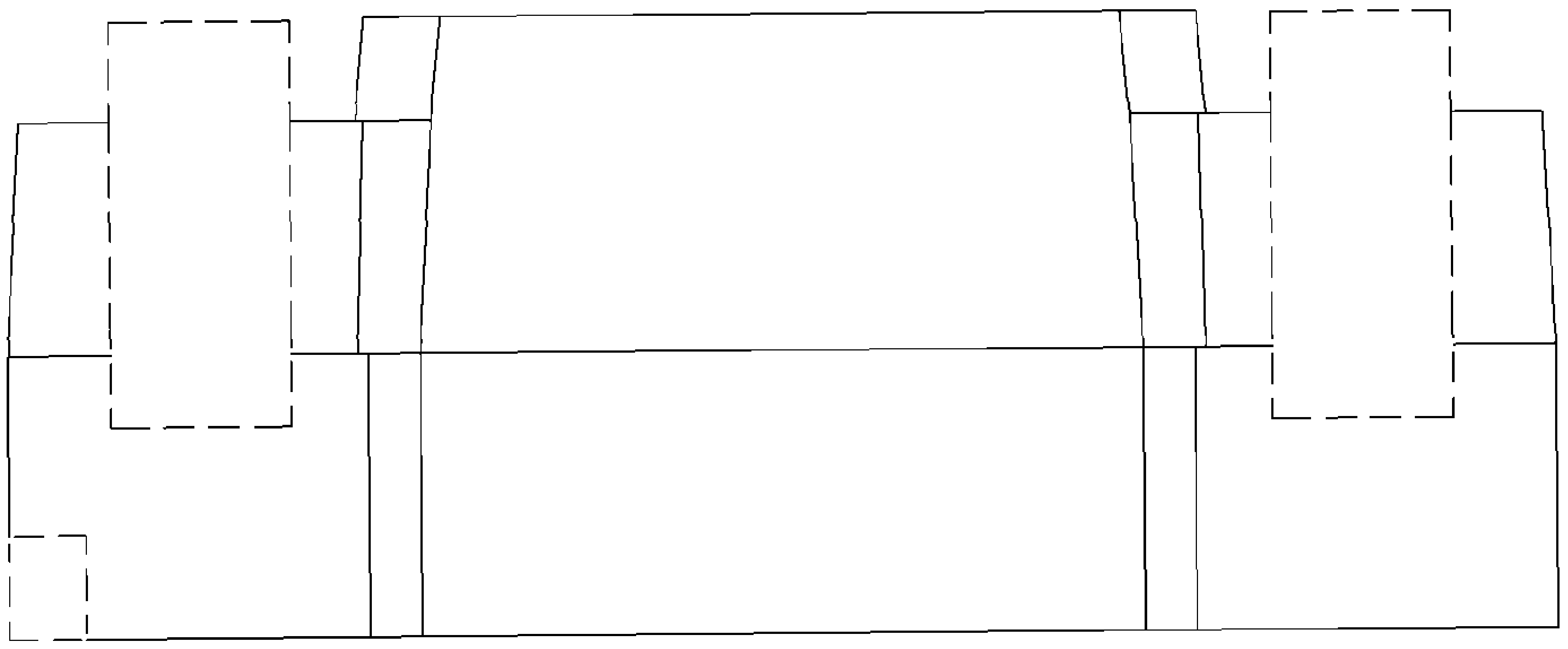


FIG. 6